

Release Notes DA1469x SDK

SW-B-001

Abstract

This document contains the release notes for Dialog Semiconductor's DA1469x Software Development Kit, version 10.0.8.105



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1 Terms and Definitions

API	Application Programming Interface
BLE	Bluetooth Low Energy
DMA	Direct Memory Access
FPGA	Field Programmable Gate Array
FW	Firmware
GA	General access
HCI	Host Controller Interface
IRQ	Interrupt Request
LA	Limited access
NVMS	Non Volatile Memory Storage
OS	Operating System
OTP	One Time Programmable memory
PLT	Production Line Tool
SDK	Software Development Kit
SNC	Sensor Node Controller
SUOTA	Software Update Over The Air
TRNG	True Random Number Generator
ТХ	Transmit
USB	Universal Serial Bus

2 Release Data

Table 1: Information Table

Software	SDK10 (DA1469x SDK)
Device Number	DA14691, DA14695, DA14697, DA14699
Software Release Date	17 January 2020
Software Version Number	10.0.8.105
Software Release Type (Note 1)	FULL (GA)

Note 1 Releases can be of the following types: FULL (GA), FULL (LA), RELEASE CANDIDATE, ENGINEERING, PATCH or BINARY

3 License

Licenses covering this SDK release are listed in the license.txt file in SDK doc folder.

4 Related Documentation and References

- [1] UM-B-090, DA1469x Getting Started with the Development Kit , Revision 2.0, User Manual, Dialog Semiconductor.
- [2] UM-B-092, DA1469x Software Platform Reference, Revision 5.0, User Manual, Dialog Semiconductor.
- [3] UM-B-131, DA1469x SDK Porting Guide, Revision 1.0, User Manual, Dialog Semiconductor

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5 Release Description

5.1 Overview

This is a full release of SDK 10.0.8 which supports the DA1469x device. It adds support from Bluetooth version 5.1, the PLT firmware project, support for haptics and audio and a number of improvements and fixes as listed in the following tables.

5.2 New and Updated Features of 10.0.8.105

Feature Number	Description	
105_01	Added PLT_FW (Production Line Tool) application	
105_02	Added Audio Manager middleware component for configuring audio paths. A demo application (apu_demo) demonstrating its' usage was also included	
105_03	Added Smartdrive and Waveform playback support for Haptics	
105_04	Support for HCI_LE_Generate_DHKey [v2]. This is a new HCI command introduced as part of v5.1 Bluetooth specification, which enhances the device to initiate generation of a Diffie-Hellman key in the Controller using a pre-defined debug private key when the Security Manager is operated in Debug Mode	
105_05	Support for Link Layer Privacy feature added. This is v4.2 Bluetooth feature which allows the Bluetooth Controller to generate and resolve the resolvable private address (RPA) during various BLE operational states. Future SDK release will provide necessary support in Bluetooth Host	
105_06	Support for interleaving of non-connected BLE operational states (Advertising, Initiating, Scanning). This allows application to simultaneously enable all these operations	
105_07	Automatic generation of Public-Private Key generation during Phase 1 of the pairing process resulting in fresh key pair at every pairing procedure and thereby increases the security of the product. This is in line with the recommendation of Bluetooth specification	
105_08	New stack versioning scheme reflecting unique value for each stack library implementation that is reflected in LL_VERSION_IND	
105_09	Bluetooth Controller and Host stack has been upgraded to Core Specification v5.1	
105_10	Controller Subsystem: Compliant to Core Specification v5.1 with the requirements set by Test Case Reference List (TCRL) 2019-1. QDID : 139842	
105_11	Host Subsystem: Compliant to Core Specification v5.1 with the requirements set by Test Case Reference List (TCRL) 2019-1. QDID : 125630	

Table 2: 10.0.8.105 New Features

5.3 Fixes and Improvements since 10.0.6.90

Table 3: 10.0.8.105 Fixes and Improvements

Description
Improved the system behaviour of the stack while sending packets during connection establishment procedure to reduce the possibility of link loss
Improved SNC API for getting uptime ticks
Improved GD25LE series flash devices current consumption in standby mode
Improved USB port and data contact detection
Improved IS_OTP_ADDRESS macro implementation



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Fix Number	Description	
105/06	Fixed bus error in SDADC adapter	
105/07	Fixed system not going to sleep when adapters fail to open (return error)	
105/08	Fixed P0_23 GPIO pin configuration as external LP_CLK input	
105/09	Extended QSPI memory configuration API for setting fast read opcode	
105/10	Fixed OTP CS BD_ADDRESS mapping in SmartSnippets Toolbox	
105/11	Removed configurations which are not applicable for the DA1469x family of devices from SDK application configuration files	
105/12	Fixed breakpoints not set when debugging in PRODUCTION MODE	
105/13	Aligned Hibernation and Deep Sleep power configuration with datasheet description	
105/14	Removed ASSERT_WARNING halting execution (in Development Mode) when an unknown CS group id is found in OTP	
105/15	Improved device configuration: splited bsp defaults per device and refactored device selection (dg_configDEVICE macro)	
105/16	Set cli_programmer default uart baudrate to 1MBps	
105/17	Improved GPADC driver implementation and fixed API typos	
105/18	Fixed ad_sdadc input validity checks	
105/19	Fixed program_qspi_nvparam script failing to program nv params when no application specific NV parameters exist	
105/20	Fixed wrong calculation of watchdog margin resulting in spontaneous ASSERT_WARNING hit when going to sleep	
105/21	Fixed SDK BLE applications requesting to start adevertise when max supported number of connections is reached	
105/22	Improved the stack behaviour during setting of data length (HCI_Set_Data_Length command) and Data Length Update procedure to address to improve interoperability	
105/23	Improved the system behaviour of the stack to address the collisions during link layer Procedures using Instants	
105/24	Improved the handling of LL_REJECT_IND and LL_REJECT_EXT_IND PDUs during various Link layer procedures resulting in better interoperability against the devices which rejects the link layer commands	
105/25	Added a true number generated from TRNG block as a seed to the random number generator for CMAC. This prevents the controller to generate same random private device address.	
105/26	In RF Test mode, only packets with correct CRC is used for estimating RSSI	
105/27	The upper limit (maximum length) of duplicate filtering list is added to the CMAC Configuration table allowing SDK to set the value statically from dg_configBLE_DUPLICATE_FILTER_MAX. This means the upper limit (maximum length) of duplicate filtering list can not be set through HCI_DBG_Wr_Filt_Dup_Size command	
105/28	Initiation of Link layer procedures honours the remote device Link layer FeatureSet	
105/29	Re-initiation of LE Ping Procedure even after receiving LL_UNKNOWN_RSP PDU for previously initiated LL_PING_REQ (Bluetooth Specification v5.1 Errata 12901)	
105/30	Optimal usage of Connection Event to allow maximum time between receiving and transmitting packet within an connection event when operating in slave role for a BLE connection. This increases the data throughput while receiving bulk data in slave role for a BLE connection	
105/31	Fixed issue : Possible occurrence of hard fault in CMAC, when the LL_CONNECTION_PARAM_REQ for the second BLE connection was sent immediately after the connection establishment and was rejected by the peer device	

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Fix Number	Description
105/32	Fixed issue : BLE Connection was deemed as lost (i.e. link lost) even before the expiry of link supervision timeout due to 10 msec resolution of the timer
105/33	Fixed issue : Termination of Pairing Procedure due to DH Key mismatch is not communicated to peer device
105/34	Fixed issue : A Data Physical Channel Packet was not considered as "received" when the Access Address is correct, but fails CRC. This can lead to BLE Connection prematurely classified as lost (i.e. link lost)
105/35	Fixed issue : Incorrect handling of Link Layer Procedure collisions resulting in abnormal handling of future Link Layer procedure which rarely can lead to link loss
105/36	Fixed issue : Incorrect usage of variable/operator results in assertion of PLT firmware immediately after HCI_DBG_GET_CAL_RESULT command
105/37	Fixed issue : As master of the BLE Connection, the slave's symmetrical PHY request is incorrectly handled during PHY Update Procedure
105/38	Fixed issue : Premature changing of internal state prior to validating all the parameters of Test command in PLT firmware can lead to incorrect or missing response for HCI_DBG_Tx_Test_Enh command
105/39	Fixed issue : Crossover (allowed collision) of Link layer procedures can lead to non- handling of link layer PDU
105/40	Fixed issue : Initial full RF calibration is performed when XTAL32M is in TRACKING mode rather than in HOLD mode. This may affect RF calibration if booting of CMAC happens under low temperatures
105/41	Fixed issue : Incorrect response sent for the ATT PDU Requests received with unsupported Attribute Opcode
105/42	Fixed issue : Incorrect handling on reception of wrongly formed Security Manager Protocol PDU (i.e packet which are less than what is expected for a specific opcode but with correct L2CAP length)
105/43	Fixed issue : Pairing may succeed with peer device supporting only lower security levels when Secure Connections Only Mode (Security Mode 1 Level 4 as defined by GAP specification) is selected
105/44	Fixed issue : When LE Secure Connection is used for pairing, the pairing succeeds even if the required key size of 16 bytes is not met
105/45	Fixed issue : When privacy feature is enabled, the host stack asserted if a wrong device addressing (static device address) is set during passive scanning
105/46	Fixed issue : Minimum and maximum connection interval parameter specified in LL_CONNECTION_PARAM_REQ may be different to that specified by the application
88.01	Compensate RTC when RCX is used as LP clock
88.02	Fixed generation of same Private Random Resolvable Address after system reset

5.4 Known Issues of 10.0.8.105

Table 4: 10.0.8.105 Known Issues

Issue Number	Description
105.01	PLT_FW hci_gpio_wd and hci_gpio_set commands may result in unexpected behavior when PWM option is used. Also hci_cmd_sleep command should not be called after these commands when PWM option is used
105.02	PLT_FW hci_sensor_test command fails to write register values over the SPI bus
105.03	Changing system clock speed is not thread safe (cm_sys_clk_set() should not be concurrently called by multiple tasks)

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Issue Number	Description
105.04	Voltage monitoring service (sys_adc) always monitors temperature sensor near radio (sys_adc_config() temperature sensor selection is ignored)
105.05	PMU adapter loads default settings to BOD
105.06	ANCS application becomes unresponsive in out of range and stress tests
66.02	Assertion will hit during USB suspend/resume if reset is received before resume
28.04	Detaching from Eclipse Debugger is not always successful

5.5 Known Limitations of 10.0.8.105

Table 5: 10.0.8.105 Known Limitations

Limitation Number	Description
105.07	Only 8 set of Identity Resolving Key (IRK) is supported in the resolving list at Link Layer when privacy feature is used
105.08	Controller stack does not alter the minimum and maximum connection interval provided by the application for LL_CONNECTION_PARAM_REQ. This can lead to scheduling conflicts during multi-connection. Workaround: Set identical value for minimum and maximum connection interval from application to trigger controller to choose a value with minimal scheduling conflicts in multi-connection scenarios
105.09	Controller stack reports hardware error and become unresponsive when the host sends an ACL data packet of length higher than the maximum size reported in the response of HCI_LE_Read_Buffer_Size command that the controller can receive from host. This can happen only when external host stack is used
105.10	Controller stack asserts when the ACL data packet is received from the host with the connection handle which is specified as Reserved for Future Use (RFU) in Bluetooth specification. This can happen only when external host stack is used
105.11	The APIs for supporting haptic and audio are in beta state. API's may change in future SDK releases
16.10	Default version of Segger debugger does not support Watchpoints



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6 Release History

6.1 Version 10.0.6.90

6.1.1 Overview

This is a full release of SDK 10.0.6 which supports the DA1469x device. It adds support in the OTP configuration script for XTAL trim values and BD address.

6.1.2 Fixes and Improvements since 10.0.6.88

Table 6: 10.0.6.90 Fixes and Improvements

Fix Number	Description
0066/01	Support XTAL32M trim settings from OTP Configuration Script
0090.02	Bluetooth BD Address can be stored in OTP Configuration Script

6.1.3 Known Issues of 10.0.6.90

Table 7: 10.0.6.90 Known Issues

Issue Number	Description
0088.01	When RCX is used as an LP clock, the RTC is not compensated according to the calculated frequency of the RCX.
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0028.04	Detaching from Eclipse Debugger is not always successful

6.1.4 Known Limitations of 10.0.6.90

Table 8: 10.0.6.90 Known Limitations

Limitation Number	Description
0088.02	After system reset the same Private Random Resolvable Address is generated
0016.10	Watchpoints not yet supported by Segger debugger



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6.2 Version 10.0.6.88

Version 10.0.4.88 of SDK was released on August 2nd, 2019

6.2.1 Overview

This is a full release (Note 1) of 10.0.6 SDK that runs on the DA1469x devices. It can be used for application development, testing and production.

6.2.2 New and Updated Features of 10.0.6.88

Table 9: 10.0.6.88 New Features

Feature Number	Description
320_03	Added support for using RCX as low power clock
322_03	Added API for controlling radio TX power
114_07	Added support for BLE (CMAC) reset

6.2.3 Fixes and Improvements since 10.0.4.66.2

Table 10: 10.0.6.88 Fixes and Improvements

Fix Number	Description
0088/01	Added ble_cli demo project
0088/02	Added mtb contents in memory dump (collect_debug_info script)
0088/03	Use same ccc value length (2) in all services
0088/04	Upgrade to CMSIS v5.5.1
0088/05	Improve power consumption by dynamically adjusting the level of the V12 rail.
0088/06	Improve the measurements for all the GPADC temperature channels using empirical calibration data.
0088/07	Extend the Stack Pointer (SP) range check in HardFault_Handler() taking into account the PSRAM presence.
0088/08	Allow user to explicitly issue an I2C RESTART regardless of whether or not the transfer direction is changing.
0088/09	Add flow control to BLE security requests
0088/10	Improve hogp_host by being able to provide the connection id as user input
0088/11	Handle improper BD address user input in ble_multi_link project
0088/12	Update the register CMSIS files to match the datasheet description
0088/13	Fixed image flashing using Toolbox
0088/14	Fixed charger's EoC current threshold values (align with chip characterization data)
0088/15	Fixed overflow in portCONVERT_MS_2_TICKS, portCONVERT_TICKS_2_MS macro calculations for timer values over 4.295 seconds (at a typical tick-rate of 1KHz).
0088/16	Fixed low level driver hw_smotor_get_fifo_command(uint8_t index) API reading of Step Motor Controller FIFO contents
0088/17	Fixed double issuing of flash power down command when entering extended sleep
0088/18	Fixed bus-fault upon re-configuration of SDADC adapter when HW_SDADC_VREF_INTERNAL is used as vref_voltage
0088/19	Fixed check for active PLL in Power Management Unit low level driver when shutting down 1V4 rail is requested

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Fix Number	Description
0088/20	Fixed race condition in DMA configuration resulting in clearing DMA INT enable
0088/21	Fixed the procedure for detecting the VBUS state (attach or detach).
0088/22	Fixed overflow when converting XTAL32M Ready IRQ counter cycles to LP clock cycles
0088/23	Fixed misconfiguration of LRA haptic block improving driving performance
0088/24	Fixed hw_i2c_write_buffer_sync() to block until all bytes have been transmitted.
0088/25	Fixed not being able to start advertising for a 2nd time when a PRIVATE_RANDOM_RESOLVABLE_ADDRESS address is used.
0088/26	Fixed not being able for an application to get a BLE_EVT_GAP_CONNECTED event, if a disconnection happens while the address resolution is in progress.
0088/27	Fixed a pending update request for one connection preventing a new update procedure on another.
0088/28	Fixed hw_timer_configure_pwm() not enabling correctly the TIMER and TIMER2 PWM output pin during sleep.
0088/29	Fixed clock configuration in SNC I2C driver in order to support a transaction with high speed configuration.
0066.03	Fixed issue with L2CAP start fragments with length < 4 bytes

6.2.4 Known Issues and Limitations of 10.0.6.88

Table 11: 10.0.6.88 Known Issues

Issue Number	Description
0088.01	When RCX is used as an LP clock, the RTC is not compensated according to the calculated frequency of the RCX.
0088.02	After system reset the same Private Random Resolvable Address is generated
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



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6.3 Version 10.0.4.66.2

Version 10.0.4.66.2 of SDK was released on April 24th, 2019

6.3.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included source code labelling corrections and updates.

6.3.2 New and Updated Features of 10.0.4.66.2

Table 12: 10.0.4.66.2 New Features

Feature Number	Description
-	No new features were added in this release

6.3.3 Fixes and Improvements since 10.0.4.66.1

Table 13: 10.0.4.66.2 Fixes and Improvements

Fix Number	Description
0066.2/01	Added workaround for errata issue 304 ("PLL calibration does not work properly")

6.3.4 Known Issues and Limitations of 10.0.4.66.2

Table 14: 10.0.4.66.2 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



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6.4 Version 10.0.4.66.1

Version 10.0.4.66.1 of SDK was released on April 17th, 2019.

6.4.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included source code labelling corrections and updates.

6.4.2 New and Updated Features of 10.0.4.66.1

Table 15: 10.0.4.66.1 New Features

Feature Number	Description
-	No new features were added in this release

6.4.3 Fixes and Improvements since 10.0.4.66

Table 16: 10.0.4.66.1 Fixes and Improvements

Fix Number	Description
0066.1/01	Source code labelling corrections and updates
0066.1/02	Remove obsolete SD-ADC clock selection option HW_SDADC_CLOCK

6.4.4 Known Issues and Limitations of 10.0.4.66.1

Table 17: 10.0.4.66.1 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



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6.5 Version 10.0.4.66

Version 10.0.4.66 of SDK was released on February 22nd, 2019.

6.5.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included a number of fixes and improvements, as listed below.

6.5.2 New and Updated Features of 10.0.4.66

Table 18: 10.0.4.66 New Features

Feature Number	Description
-	No new features were added in this release

6.5.3 Fixes and Improvements since 10.0.2.60

Table 19: 10.0.4.66 Fixes and Improvements

Fix Number	Description
0066/01	Added support for USB Development Kit
0066/02	Support maximum image size loading over serial boot (128Kb)
0066/03	Fix unhandled pending read event in uart adapter
0066/04	Fix PM sleep_mode handling
0066/05	Fix handling of charging events on sys_charger
0066/06	Fix GPADC channel enumeration
0066/07	Fix cscp heap issues
0066/08	Fix waiting forever in I2C adapter forced close
0066/09	Fix BLE_EVT_GAP_DATA_LENGTH_SET_FAILED event in ble/mgr/gap
0066/10	Improved robustness of BLE controller
0066/11	Remove -wnocpp compilation flag from projects
0066/12	Fix static code analysis errors
0066/13	Fix endianess issue when writting to OTP from Toolbox
0066/14	Fix qspi_is_valid_addr() to execute from RAM
0066/15	Fix possible race condition in sdadc/uart drivers
0066/16	Fix wake up from K1 in hrp_sensor
0066/17	Fix secure SUOTA failures with CRC mismatch
0066/18	Add sleep support in DGTL
0066/19	Fix unregistering interrupt callback when force closing slave in I2C adapter
0066/20	Fix gpio power configuration in I2C/SPI/LCD adapters
0066/21	Add program_qspi_nvparam launcher
0066/22	Add support for FreeRTOS thread aware debugging in eclipse
0066/23	Add protection for race condition on XTAL32M_CTRL0_REG
0066/24	Fix cache configuration errors
0066/25	Refactor cache initialization

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Fix Number	Description
0066/26	Add check for LDO_PLL_OK signal before enabling PLL
0066/27	Fix VDD voltage (0.828V) in hibernation mode
0066/28	Fix not protecting ble_storage_remove() functions
0066/29	Add API to retrieve low level stats in BLE adapter
0066/30	Fix issue while changing properties permission of BLE characteristics

6.5.4 Known Issues and Limitations of 10.0.4.66

Table 20: 10.0.4.66 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



6.6 Version 10.0.2.60

Version 10.0.2.60 of SDK was released on Januart 14th, 2019.

6.6.1 Overview

This was a full release of 10.0.2 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included a number of fixes and improvements, as listed below.

6.6.2 New and Updated Features of 10.0.2.60

Table 21: 10.0.2.60 New Features

Feature Number	Description
912_02	Refactored Peripheral Adapters API
322_01	Updated radio driver

6.6.3 Fixes and Improvements since 10.0.1.52

Table 22: 10.0.2.60 Fixes and Improvements

Fix Number	Description
0060/01	Set default Vdd to 1V2
0060/02	Added automatic BLE security key renewal for DA1469x
0060/03	Added support for Uart 3 in UART adapter
0060/04	Added SDADC adapter
0060/05	Enable static GPIO power configuration support when SNC is used
0060/06	Added create flash image python script
0060/07	Fixed OSAL calls depending on execution context (simple task or ISR)
0060/08	Support BLE 2Mbit high performance radio mode
0060/09	Improved robusteness of BLE controller / host
0060/10	Use HW_SPI_FIFO_RX_TX in spi adapter write calls
0028.09	SDK uses TRNG for generating random numbers
0028.07	Bond Management Service (BMS) example gives a new random key after reset
0052.01	Added support for SCA and other BLE parameters in NVPARAMS

6.6.4 Known Issues and Limitations of 10.0.2.60

Table 23: 10.0.2.60 Known Issues

Issue Number	Description	
0060.01	Removed plt_fw project from release files	
0028.04	Detaching from Eclipse Debugger is not always successful.	
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.	
0016.10	Watchpoints not yet supported by Segger debugger.	



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6.7 Version 10.0.1.52

Version 10.0.1.52 of SDK was released on December 7th, 2018.

6.7.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and testing.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to run on the official SDK release once that becomes available.

This release included a number of fixes and improvements, as well as a number of new features, as listed below.

6.7.2 New and Updated Features of 10.0.1.52

Feature Number	Description	
131_02	AMS Client Profile	
120_14	HD Service	
130_14	CP 1.0: Cycling Speed and Cadence Profile - Collector	
510_08	Aicro Trace Buffer support	
450_04	Support USB charging, including enumeration	
440_01	CDC serial over USB	
440_03	MSD over USB	
420_04	Added security framework for AES/Hash/ECC/TRNG algorithms	

Table 24: 10.0.1.52 New Features

6.7.3 Fixes and Improvements since 10.0.1.39

Table 25: 10.0.1.52 Fixes and Improvements

Fix Number	Description	
0028.03	SUOTA stability issues have been observed with stress tests.	
0028.05	Removed unneeded clock pulses after byte read command in SPI adapter.	
0031.02	Improved stability of pxp_reporter application under stress testing.	
0031.04	Improved robustness in ble_multi_link application.	
0039.02	Sleep is now blocked while a DMA transfer is in progress	
0039.03	Fixed transaction abort issue in Sensor Node Controller driver for I2C	
0052/01	Improved robustness of BLE Controller & Host	
0052/02	Updated Power and clock management for stability	
0052/03	Updated NMVS to add power-safety	
0052/04	Improved radio performance	
0052/05	Added a board abstraction layer	
0052/06	Refactored USB Framework	
0052/07	Added support for external OSC as LP clock	
0052/08	Extend & refactor SENIS API	
0052/09	Support USB suspend/resume	

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Fix Number	Description
0052/10	Extend ERM driver API
0052/11	Add suppport for JLink Flashing tool
0052/12	Add support for secure boot in python scripts
0052/13	Restore GPADC configuration after sleep
0052/14	plt_fw: Fix code location in custom_config_ram
0052/15	aes_hash: Add support for reading keys form OTP
0052/16	Support new 4MB flash partition layout

6.7.4 Known Issues and Limitations of 10.0.1.52

Table 26: 10.0.1.52 Known Issues

Issue Number	Description	
0052.01	Sleep clock accuracy can only be configured complile time, not through NVMS	
0028.04	Detaching from Eclipse Debugger is not always successful.	
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.	
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.	
0028.09	TRNG is not used by the SDK for generating random numbers.	
0016.10	Watchpoints not yet supported by Segger debugger.	



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6.8 Version 10.0.1.39

Version 10.0.1.39 of SDK was released on September 28th, 2018.

6.8.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included code for low level access to the LRA and Motrol Controller peripherals, moves to the GCC v7 and improves overall maturity.

6.8.2 New and Updated Features of 10.0.1.39

Table 27: 10.0.1.39 New Features

Feature Number	Description	
112_04	upport for Channel Selection Algorithm #2	
328_01	itial implementation of a low level driver for LRA	
328_06	Initial implementation of a low level driver fo Motor Controller	
460_03	QSPI Flash/RAM Adapter	
510_02	Upgrade to GNU/GCC version 7	

6.8.3 Fixes and Improvements since 10.0.1.32

Table 28: 10.0.1.39 Fixes and Improvements

Fix Number	Description	
0031.01	Configuration option allows to select TX power of 0dB or 6dB for a project	
0031.03	Increased application stability seen in stress tests.	
0016.04	Cleanup of release files to minimise references to DA1468x SDK.	
0016.05	Restructured Doxygen documentation	
0016.09	Added calibration support for values returned by the GPADC driver.	
0039/01	Improved RSSI read command	
0039/02	Upgraded to latest version of BLE Stack Library	
0039/03	Enable reading configuration data from OTP as default.	
0039/04	Restructured SDK folders	
0039/05	Fixed high speed transaction issue in SNC i2c driver	

6.8.4 Known Issues and Limitations of 10.0.1.39

Table 29: 10.0.1.39 Known Issues

Issue Number	Description	
0039.01	Qspi LLD Api changed to support QSPI2 interface (impacts backwards compatibility)	
0039.02	Sleep is not blocked while a DMA transfer is in progress.	
0039.03	Issue in Sensor Node Controller driver for I2C with transaction abort.	
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Issue Number	Description	
0031.02	pxp_reporter application stability issues have been observed in stress tests.	
0031.04	ble_multi_link application sometimes fail to report device disconnection.	
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.	
0028.03	SUOTA stability issues have been observed with stress tests.	
0028.04	Detaching from Eclipse Debugger is not always successful.	
0028.05	SPI adapter creates unneeded clock pulses after byte read command.	
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.	
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.	
0028.09	TRNG is not used by the SDK for generating random numbers.	
0016.10	Watchpoint support for debugging is not included.	

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6.9 Version 10.0.1.32

Version 10.0.1.32 of SDK was released on May 25th, 2018.

6.9.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included more BLE examples, moves to the latest FreeRTOS v10.0.1 and improves overall maturity. A detailed list of new features is given below.

6.9.2 New and Updated Features of 10.0.1.32

Table 30: 10.0.1.32 New Features

Feature Number	Description
111_04	Efficient non connectable advertising – CSSv6
111_01	LE Secure Connection
112_05	High duty cycle non connectable advertising
114_01	Multilink support
400_01	Update to FreeRTOS 10.0.1
120_09	CSCS 1.0: Cycling Speed and Cadence Profile
130_24	HRP 1.0:: Heart Rate Profile - Collector
130_21	HOGP 1.0: HID Over GATT Profile - HID Device
130_22	HOGP 1.0: HID Over GATT Profile - Host
520_01	Production test firmware BLE test commands
610_07	BLE Multilink
610_06	BLE External Host

6.9.3 Fixes and Improvements since 10.0.1.28

Table 31: 10.0.1.32 Fixes and Improvements

Fix Number	Description	
0031/01	Enabled –werror (warnings are reported as errors) compiler option and cleaned up warnings in SDK apps.	
0028.08	ixed BMS stability issues observed when more than 1 connection is active.	
0028.10	Fixed support for PRODUCTION mode.	
0028.11	Fixed waking up from button in SDK apps.	
0016.07	Added temperature-triggered calibration in Radio driver.	

6.9.4 Known Issues and Limitations of 10.0.1.32

Table 32: 10.0.1.32 Known Issues

Issue Number	Description	
0031.01	Radio TX power is fixed to 0dB.	
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Issue Number	Description		
0031.02	pxp_reporter application stability issues have been observed in stress tests.		
0031.03	gp_device application stability issues have been observed in stress tests.		
0031.04	ble_multi_link application sometimes fail to report device disconnection.		
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.		
0028.03	SUOTA stability issues have been observed with stress tests.		
0028.04	Detaching from Eclipse Debugger is not always successful.		
0028.05	SPI adapter creates unneeded clock pulses after byte read command.		
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.		
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.		
0028.09	TRNG is not used by the SDK for generating random numbers.		
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.		
0016.05	Doxygen documentation still includes references to DA1468x SDK.		
0016.09	Values returned by the GPADC driver are not calibrated.		
0016.10	Watchpoint support for debugging is not included.		



6.10 Version 10.0.1.28

Version 10.0.1.28 of SDK was released on March 22nd, 2018.

6.10.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included more BLE features, a set of crypto algorithms, and more low level drivers for peripherals on DA1469x, It also adds configuration of the integrated HW charger and system support for sleep mode. A detailed list of delivered features is given below.

6.10.2 New and Updated Features of 10.0.1.28

Feature Number	Description			
110_01	LE Scatter net.			
111_01	LE Secure Connection.			
111_03	Enhanced Privacy 1.2.			
120_32	WSS 1.0 : Weight Scale Service.			
130_23	HRP 1.0: Heart Rate Profile.			
130_43	WSP 1.0: Weight Scale Profile.			
131_01	Apple Notification Center Service (ANCS) Client.			
320_01	Clock and Power Management Low Level Driver.			
320_02	Charger Low Level Driver.			
321_02	AES Low Level Driver.			
321_03	HASH Low Level Driver.			
321_04	TRNG Low Level Driver.			
326_06	USB Charger Low Level Support.			
326_09	UART3 Low Level Driver.			
328_06	ADC 1 Low Level Driver.			
328_07	ERM Low Level Driver.			
328_08	ADC 2 Low Level Driver.			
400_02	FreeRTOS Tick-less Mode.			
420_04	Security Framework (AES/ECC Crypto, TRNG).			
420_05	Algo - Random Number Generation.			
420_06	Algo - Hash Bytes.			
420_07	Algo - Hash - Key Derivation.			
420_08	Algo - Hash - HMAC Generation.			
420_09	Algo - AES - Encrypt/Decrypt.			
420_12	Algo – ECDH Generate/Verify Public/Session Key			

Table 33: 10.0.1.28 New Features

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Feature Number	Description	
450_03	System Management – Watchdog Service.	
450_04	ystem Management – Charger Service.	
460_02	rypto Adapter.	

6.10.3 Fixes and Improvements since 10.0.1.16

Table 34: 10.0.1.28 Fixes and Improvements

Fix Number	Description	
0016.01	lded support for sleep mode. Demonstrated in pxp_reporter example.	
0016.02	roved test coverage for the Bluetooth Framework.	
0016.03	mproved test coverage for drivers and SDK core.	
0016.08	Added implementation of BLE Secure Connections and Enhanced Privacy features.	
0016.06	Added support for multiple BLE connections.	

6.10.4 Known Issues and Limitations of 10.0.1.28

Table 35: 10.0.1.28 Known Issues

Issue Number	Description		
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.		
0028.02	Radio TX power is fixed to 6dB.		
0028.03	SUOTA stability issues have been observed with stress tests.		
0028.04	Detaching from Eclipse Debugger is not always successful.		
0028.05	SPI adapter creates unneeded clock pulses after byte read command.		
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.		
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.		
0028.08	BMS stability issues have been observed when more than 1 connections are active.		
0028.09	TRNG is not used by the SDK for generating random numbers.		
0028.10	PRODUCTION mode is not supported and should not be used.		
0028.11	Waking up from button is not supported in SDK apps.		
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.		
0016.05	Doxygen documentation still includes references to DA1468x SDK.		
0016.07	Radio driver does not yet include calibration. Performance may be suboptimal.		
0016.09	Values returned by the GPADC driver are not calibrated.		
0016.10	Watchpoint support for debugging is not included.		



6.11 Version 10.0.1.16

Version 10.0.1.16 of DA1469x SDK was released on February 7th, 2018

6.11.1 Overview

This was the first internal engineering release of 10.0.1 SDK that runs on the DA1469x devices. It should only be used for enabling silicon bring up and getting familiar with the SDK structure.

Please do not use this release for application development because APIs might change. Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

The DA1469x SDK is based on the Black Orca SDK architecture that supports DA1468x devices. Similar constructs with the DA1468x SW architecture include:

- i. FreeRTOS Operating System
- ii. Code execution in-place from QSPI Flash
- iii. BLE Framework that reuses the Adapter/Manager Layers and exposes the same API
- iv. Abstraction layer with low level drivers and adapters for peripheral devices

This release implements basic SDK architecture, including the BLE framework and support for the Sensor Node Controller. A detailed list of delivered features is given below.

6.11.2 New and Updated Features of 10.0.1.16

Feature Number	Description		
110_02	2CAP COC		
110_03	Low Duty Cycle Advertising		
111_02	LE Data Packet Length Extension		
112_01	LE 2Mbps		
114_02	Bluetooth Host subsystem can be updated as part of full application SUOTA		
114_03	Bluetooth Controller subsystem can be updated as part of full application SUOTA		
120_03	BAS 1.0: Battery Service		
120_04	BCS 1.0: Body Composition Service		
120_06	BMS 1.0: Bond Management Service		
120_10	CTS 1.1: Current Time Service		
120_11	DIS 1.1: Device Information Service		
120_18	IAS 1.0: Immediate Alert Service		
120_16	HRS 1.0: Heart Rate Service		
120_20	LLS 1.0.1: Link Loss Service		
120_28	ScPS 1.0: Scan Parameters Service		
120_30	TPS 1.0: Tx Power Service		
121_03	Dialog Debug Service 1.1		
310_04	XiP (cached) from Flash		
323_06	QSPI Flash Driver		
323_10	NVMS partitions		
325_01	Timers Low-Level Driver		

Table 36: 10.0.1.16 New Features

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Feature Number	Description		
325_02	RTC Low-Level Driver		
325_03	Watchdog Low-Level Driver		
326_01	GPIO Low-Level Driver		
326_02	SPI 1/2/3 Low-Level Driver		
326_03	I2C 1/2 Low-Level Driver		
326_04	UART 1/2 Low-Level Driver		
326_07	CMAC Mailbox driver included in BLE library		
326_08	LCD Low Level Driver		
328_02	White LED Low-Level Driver		
328_05	Sensor Node Controller Low-Level Driver		
400_01	FreeRTOS v9		
400_07	OS Abstraction Layer		
400_08	OS Abstraction Layer - Resource Management		
430_04	Software Upgrade over BLE (SUOTA)		
460_03	Flash Adapter		
460_04	LCD Adapter		
460_05	GPADC Adapter		
460_06	I2C Adapter		
460_07	NVMS Adapter		
460_11	SPI Adapter		
460_13	UART Adapter		
460_16	Sensor Node Controller Adapter		
510_02	Supported by GNU / GCC toolset		
510_03	Supported by JTAG debugger		
510_04	Supported from Eclipse-based IDE		
510_06	Sensor node controller programming		
530_01	Works with SmartSnippets Studio & Toolbox (version 2.0)		
610_02	PXP Reporter, including SUOTA example		
620_01	SUOTA example works with Dialog Android SUOTA App		

6.11.3 Known Issues and Limitations of 10.0.1.16

Table 37: 10.0.1.16 Known Issues

Issue Number	Description	
0016.01	SDK does not support sleep mode, all projects run in always-active configuration.	
0016.02	etooth Framework has been only tested for basic BLE4.2 functionality.	
0016.03	valuation is limited to functional testing of the demo applications delivered with the DK.	
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.	
0016.05	Doxygen documentation still includes references to DA1468x SDK.	

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Issue Number	Description	
0016.06	BLE stack may be confused if two or more connections are active. Use only one connection.	
0016.07	io driver does not yet include calibration. Performance may be suboptimal.	
0016.08	BLE Secure Connections and Enhanced Privacy features are not yet supported.	
0016.09	Values returned by the GPADC driver are not calibrated.	
0016.10	Watchpoint support for debugging is not included.	

Appendix A Software Versioning Rules

This describes the software version numbers and does not apply to documentation version numbers (as found in the footer of this document).

Each software version number string consists of four numbers: MAJOR. BRANCH. MINOR. and BUILD.

#MAJOR: It is increased (by one only) if the project undergoes a major modification, for example major ROM changes. It usually changes only when the project sources undergo major restructuring affecting most of the repository. It is initialized at 1.

#BRANCH: Used in the case of concurrent projects that for special reasons need to be spun off the major repository. It corresponds to different versions of the repository code that have to be supported concurrently. In this case each branch number corresponds to a different GIT branch. The basic project has BRANCH id 0.

#MINOR: Odd numbers indicate Engineering (or Patch or Binary) versions, even numbers indicate Full release versions or Release Candidates of Full versions. Each Full release increases this number by one. After the Full release, the number is increased by one again. Therefore, Project releases correspond to release numbers like 2.0.1.xxx, 2.0.2.xxx. etc. The #MINOR number is initialized at 1.

#BUILD: The # BUILD number increases by one at every repository update and thus indicates the total number of changes since repository initialization. The BUILD number is initialized at 1.

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Document Revision History

This section summarizes the changes made to this document and not to the Software that this document describes.

Revision	Date	Description		
13	17-Jan-2020	Fix typos		
12	23-Dec-2019	Full Release 10.0.8.105		
 New features Bug fixes and 	 Change details: New features (Haptic, Audio, BLE 5.1) Bug fixes and internal improvements Document Includes more detail on the decription of findings and improvements 			
11	27-Sep-2019	Full Release 10.0.6.90		
Change details: - Added OTP CS settings for XTAL Trim & BD Address - Split Issues and Limitations in two tables				
10	02-Aug-2019	Full Release 10.0.6.88		
9	24-Apr-2019	Added workaround for errata issue 304. Updated Disaclaimer Text. Full release 10.0.4.66.2		
8	17-Apr-2019	Remove mistaken reference to Cycling Power profile. Code Labeling fixes. Full release 10.0.4.66.1		
7	22-Feb-2019	Launch of DA1469x Family of Devices. Full release 10.0.4.66		
6	14-Jan-2019	Product Development Ready. Full release 10.0.2.60		
5	07-Dec-2018	Product Development Ready. Engineering 10.0.1.52		
4	28-Sept-2018	Improved Maturity. Engineering 10.0.1.39		
3	25-May-2018	Migrate to FreeRTOS v10. Engineering 10.0.1.32		
2	22-March-2018	Updated with more features. Engineering 10.0.1.28		
1	07-Febr-2018	Initial version. Engineering release 10.0.1.16		



Status Definitions

Status	Definition	
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.	
APPROVED or unmarked	The content of this document has been approved for publication.	

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